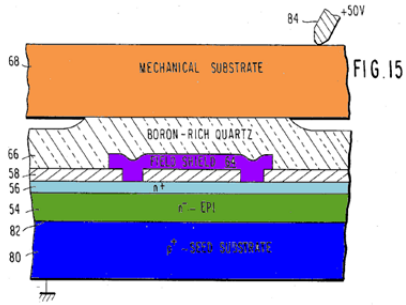
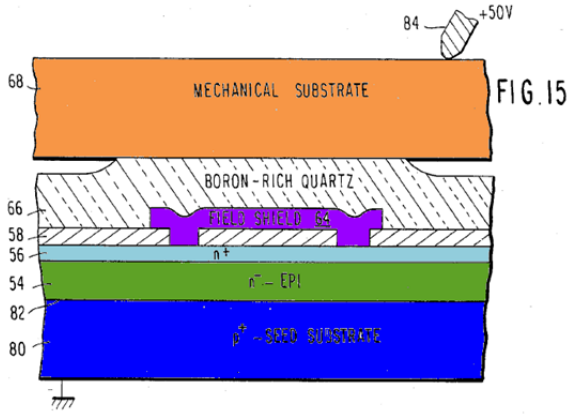
**Claims 8 and 18 of U.S. Patent No. 5,591,678 to Bendik et al. ("the '678 Patent") are obvious under 35 U.S.C. § 103 over Cade in view of U.S. Patent No. 5,002,818 to Licari et al. ("Licari")**

Prior Art Cited in this Chart:
U.S. Patent No. 4,599,792 to Cade et al. ("Cade")
U.S. Patent No. 5,002,818 to Licari et al. ("Licari")

| Claim Language | Cade in view of Licari |
|---|---|
| **Claim 8** | |
| The method of claim 1, wherein the step of attaching includes the steps of placing a layer of epoxy between the second substrate and the wafer portion of the first substrate, and degassing and curing the epoxy. | The mechanical substrate 68 of silicon is then anodically bonded to the quartz 66 by applying voltage to a voltage probe 84 with the seed substrate 80 grounded." **Cade, 7:27-30**.<br><br>**Figure 15 of Cade**<br>  <br><br><br>"An adhesive mixture reworkably adheres electronic integrated circuit dies to hybrid microcircuit substrates, and includes a thermosetting epoxy resin." **Licari, Abstract**.<br><br>"The thermosetting and thermoplastic materials were mixed by hand in the above described ratios, and outgassed prior to die attach. The dies were 0.08 inch square, and mounted on gold plated alumina substrates. All samples were outgassed again for 5 minutes after die attachment and then cured for one hour at 125°C." **Licari, 5:39-44**. |

| Claim 18 | |
|---|---|
| The method of claim 13, wherein the step of attaching includes the steps of placing a layer of epoxy between the second substrate and the front surface of the single-crystal silicon wafer, and degassing and curing the epoxy. | The mechanical substrate 68 of silicon is then anodically bonded to the quartz 66 by applying voltage to a voltage probe 84 with the seed substrate 80 grounded." **Cade, 7:27-30**.<br><br>**Figure 15 of Cade**<br>  <br><br><br>"An adhesive mixture reworkably adheres electronic integrated circuit dies to hybrid microcircuit substrates, and includes a thermosetting epoxy resin." **Licari, Abstract**.<br><br>"The thermosetting and thermoplastic materials were mixed by hand in the above described ratios, and outgassed prior to die attach. The dies were 0.08 inch square, and mounted on gold plated alumina substrates. All samples were outgassed again for 5 minutes after die attachment and then cured for one hour at 125°C." **Licari, 5:39-44**. |